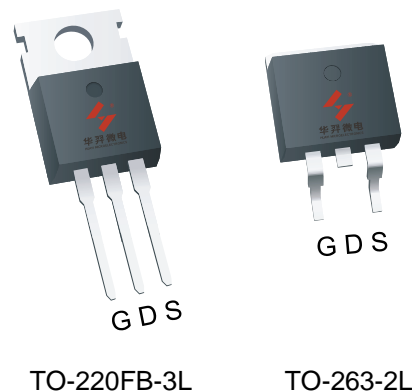


## N-Channel Enhancement Mode MOSFET

### Feature

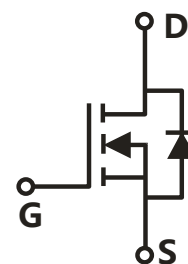
- 135V/213A  
 $R_{DS(ON)} = 4.1m\Omega(\text{typ.}) @ V_{GS} = 10V$
- 100% Avalanche Tested
- 100% DVDS
- Reliable and Rugged
- Halogen Free and Green Devices Available  
(RoHS Compliant)

### Pin Description




### Applications

- Switching application
- Li-battery protection
- DC-DC
- Motor control



Single N-Channel MOSFET

### Ordering and Marking Information

 <div style="display: inline-block; vertical-align: middle; text-align: center;"> <p>P</p> <p>HYG040N13</p> <p>XYMXXXXXX</p> </div> <div style="display: inline-block; vertical-align: middle; text-align: center; margin-left: 20px;"> <p>B</p> <p>HYG040N13</p> <p>XYMXXXXXX</p> </div>	<p>Package Code</p> <p>P:TO-220FB-3L      B:TO-263-2L</p> <p>Date Code</p> <p>XYMXXXXXX</p>
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Note: HUAYI halogen free products contain molding compounds and 100% matte tin plate Termination finish; which are fully compliant with RoHS. HUAYI halogen free products meet or exceed the halogen free requirements of IPC/JEDEC J-STD-020 for MSL classification at halogen free peak reflow temperature. HUAYI defines "Green" to mean halogen free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

HUAYI reserves the right to make changes, corrections, enhancements, modifications, and improvements to this product and/or to this document at any time without notice.

## Absolute Maximum Ratings

Symbol	Parameter		Rating	Unit
Common Ratings (Tc=25°C Unless Otherwise Noted)				
V <sub>DSS</sub>	Drain-Source Voltage		135	V
V <sub>GSS</sub>	Gate-Source Voltage		± 20	V
T <sub>J</sub>	Junction Temperature Range		-55 to 175	°C
T <sub>STG</sub>	Storage Temperature Range			°C
I <sub>S</sub>	Source Current-Continuous(Body Diode)	Tc=25°C	213	A
Mounted on Large Heat Sink				
I <sub>DM</sub>	Pulsed Drain Current *	Tc=25°C	768	A
I <sub>D</sub>	Continuous Drain Current	Tc=25°C	213	A
		Tc=100°C	151	A
P <sub>D</sub>	Maximum Power Dissipation	Tc=25°C	455	W
		Tc=100°C	227	W
R <sub>θJC</sub>	Thermal Resistance, Junction-to-Case		0.33	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient **		62.5	°C/W
E <sub>AS</sub>	Single Pulsed-Avalanche Energy ***	L=0.3mH	1381	mJ

Note: \* Repetitive rating; pulse width limited by max.junction temperature.

\*\* Surface mounted on 1in2 FR-4 board.

\*\*\* Limited by T<sub>Jmax</sub>, starting T<sub>J</sub>=25°C, L = 0.3mH, R<sub>G</sub>= 25Ω, V<sub>GS</sub>=10V.

## Electrical Characteristics(Tc =25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	HYG040N13NS1			Unit
			Min	Typ.	Max	
Static Characteristics						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>DS</sub> =250μA	135	150	-	V
I <sub>DSS</sub>	Drain-to-Source Leakage Current	V <sub>DS</sub> =135V, V <sub>GS</sub> =0V	-	-	1	μA
		T <sub>J</sub> =125°C	-	-	50	μA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250μA	2	3.3	4	V
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =± 20V, V <sub>DS</sub> =0V	-	-	±100	nA
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =10V, I <sub>DS</sub> =50A	-	4.1	5	mΩ
Diode Characteristics						
V <sub>SD</sub>	Diode Forward Voltage	I <sub>SD</sub> =50A, V <sub>GS</sub> =0V	-	0.85	1.3	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>SD</sub> =50A, dI <sub>SD</sub> /dt=100A/μs	-	117	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge		-	490	-	nC

**Electrical Characteristics (Cont.)** (Tc =25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	HYG040N13NS1			Unit
			Min	Typ.	Max	
Dynamic Characteristics						
R <sub>G</sub>	Gate Resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=500KHz	-	1.6	-	Ω
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V,	-	8308	-	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =25V,	-	3846	-	
C <sub>rss</sub>	Reverse Transfer Capacitance	Frequency=500KHz	-	63	-	
t <sub>d(ON)</sub>	Turn-on Delay Time	V <sub>DD</sub> =75V, R <sub>G</sub> =4Ω, I <sub>DS</sub> =50A, V <sub>GS</sub> =10V	-	37	-	ns
T <sub>r</sub>	Turn-on Rise Time		-	94	-	
t <sub>d(OFF)</sub>	Turn-off Delay Time		-	75	-	
T <sub>f</sub>	Turn-off Fall Time		-	93	-	
Gate Charge Characteristics						
Q <sub>g</sub>	Total Gate Charge(V <sub>GS</sub> =10V)	V <sub>DS</sub> =108V, I <sub>DS</sub> =50A	-	118	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	46	-	
Q <sub>gd</sub>	Gate-Drain Charge		-	21	-	
V <sub>plateau</sub>	Gate plateau voltage		-	5.4	-	V

Note: \*Pulse test, pulse width ≤ 300us, duty cycle ≤ 2%

## Typical Operating Characteristics

Figure 1: Power Dissipation

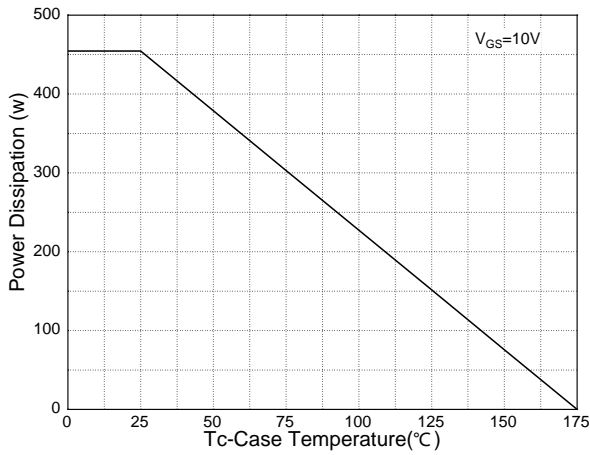


Figure 2: Drain Current

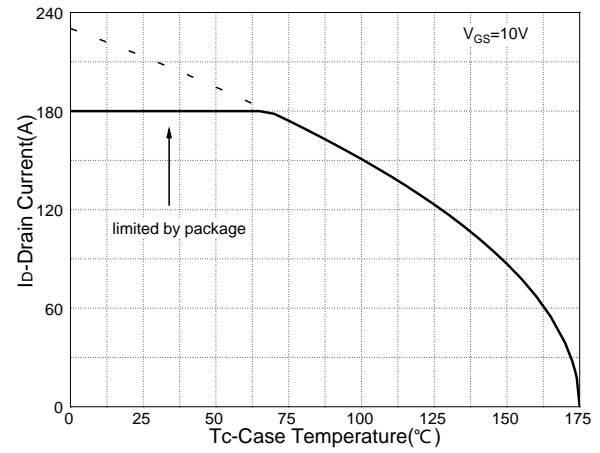


Figure 3: Safe Operation Area

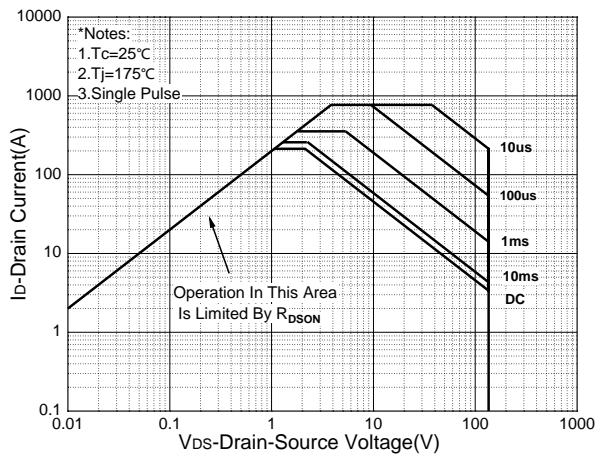


Figure 4: Thermal Transient Impedance

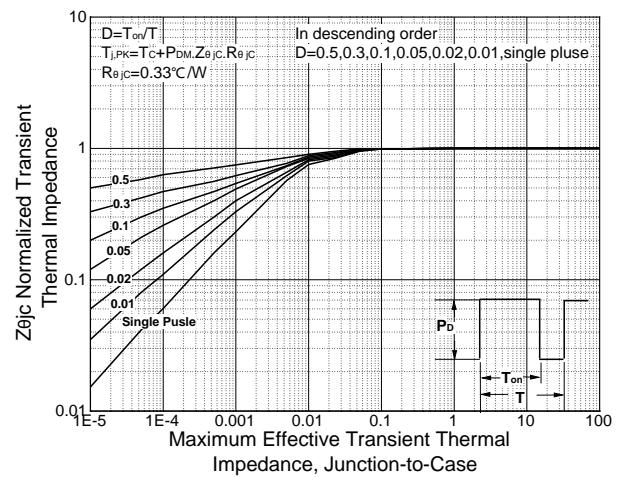


Figure 5: Output Characteristics

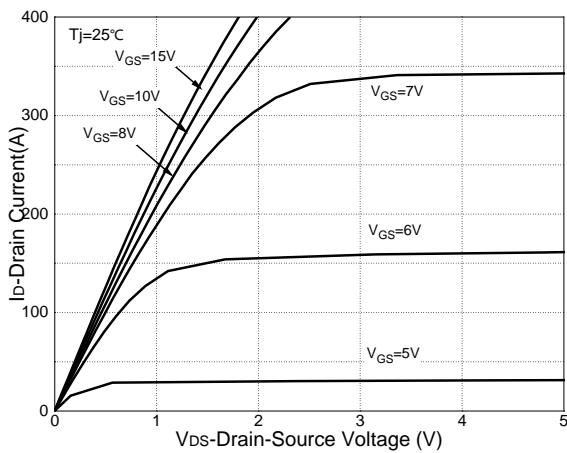
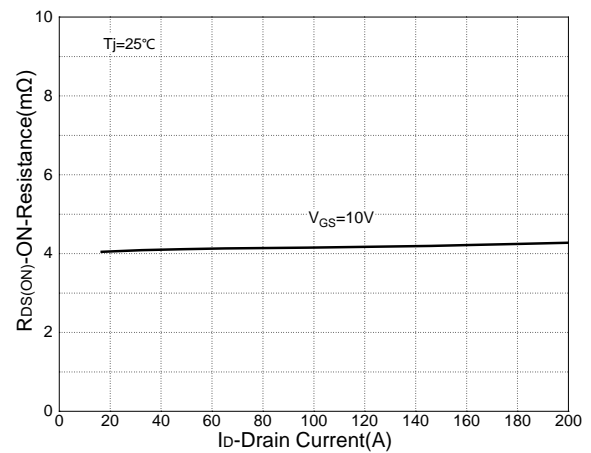


Figure 6: Drain-Source On Resistance



## Typical Operating Characteristics(Cont.)

Figure 7: On-Resistance vs. Temperature

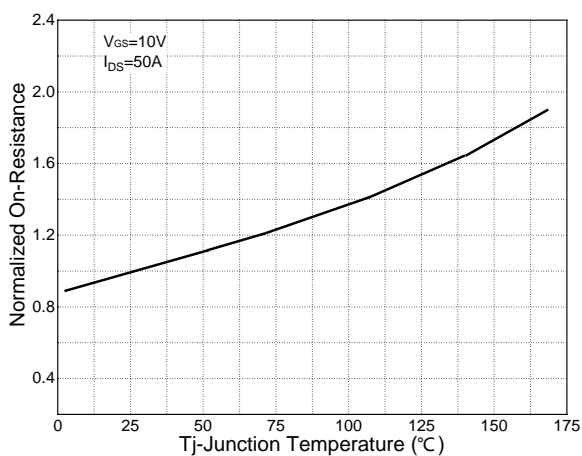


Figure 8: Source-Drain Diode Forward

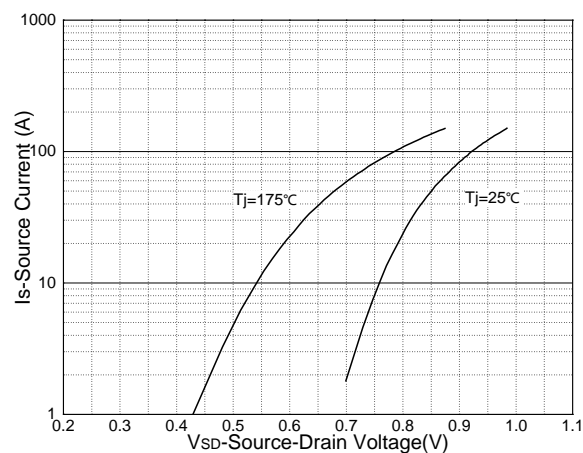


Figure 9: Capacitance Characteristics

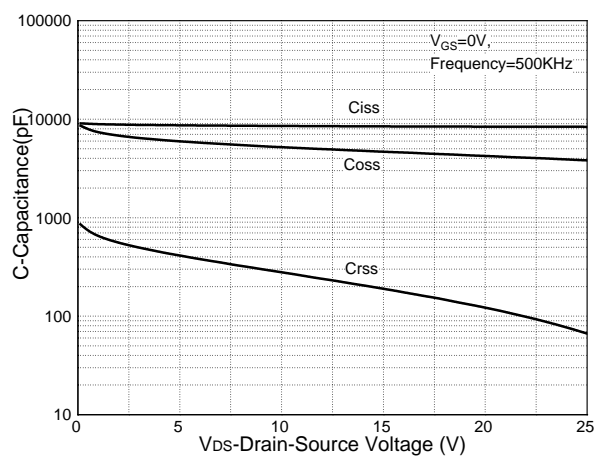
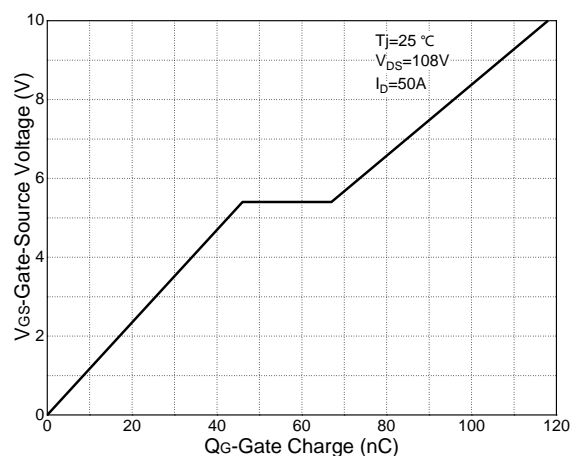


Figure 10: Gate Charge Characteristics





## Package Information

Package Type	Unit	Quantity
TO-220FB-3L	Tube	50
TO-263-2L	Reel	800

## Package Information

Technical drawing of a mechanical part, showing front and side views with dimensions.

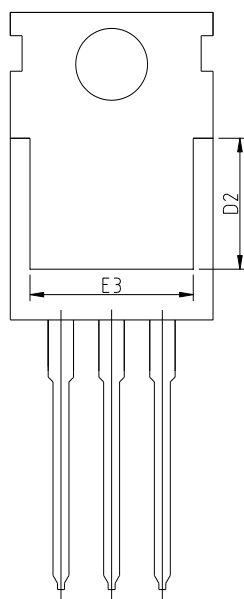
**Front View Dimensions:**

- $D$ : Total height of the part.
- $D1$ : Height of the main body.
- $E$ : Total width of the part.
- $\phi P$ : Diameter of the central hole.
- $\phi$ : Diameter of the small hole in the main body.
- $b2$ : Width of the top flange.
- $b$ : Width of the main body.
- $e$ : Width of the bottom flange.
- $e1$ : Width of the bottom flange (inner section).
- $L$ : Length of the bottom flange.
- $L1$ : Length of the main body.
- $\text{Min } 1.00$ : Minimum thickness of the bottom flange.

**Side View Dimensions:**

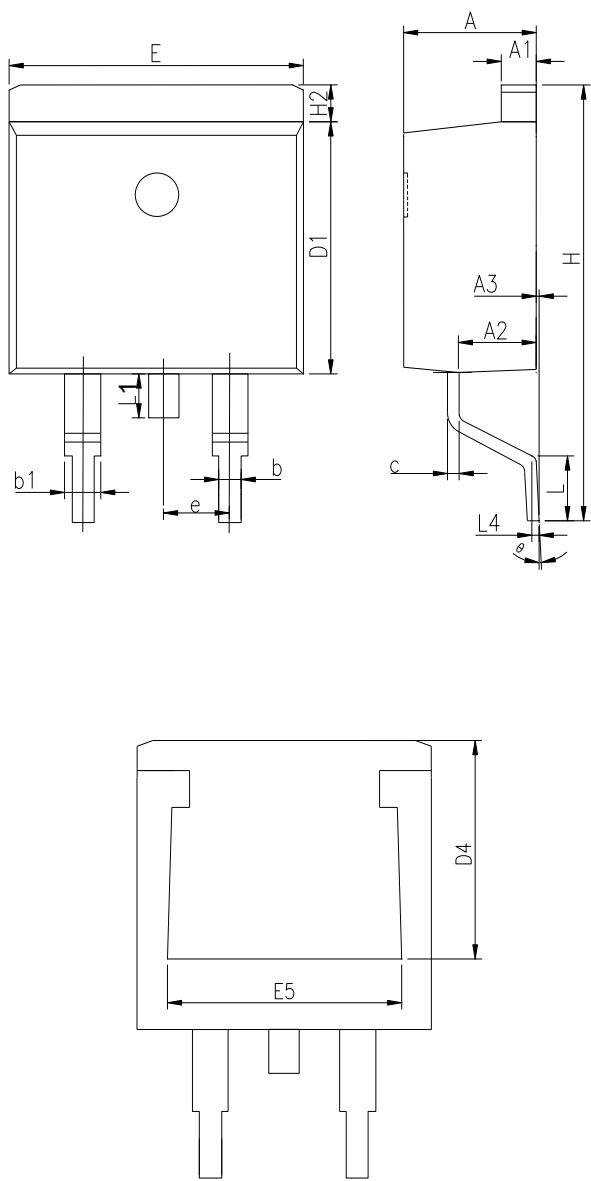
- $A$ : Total width of the part.
- $A1$ : Width of the top flange.
- $A2$ : Width of the main body.
- $C$ : Width of the bottom flange.
- $H$ : Height of the main body.

COMMON DIMENSIONS			
SYMBOL	mm		
	MIN	NOM	MAX
A	4.37	4.57	4.77
A1	1.25	1.30	1.40
A2	2.20	2.40	2.60
b	0.70	0.80	0.95
b2	1.17	1.27	1.47
c	0.45	0.50	0.60
D	15.10	15.60	16.10
D1	8.80	9.10	9.40
D2	5.50	6.30	7.10
E	9.70	10.00	10.30
E3	7.00	7.80	8.60
e	2.54 BSC		
e1	5.08 BSC		
H1	6.25	6.50	6.85
L	12.75	13.50	13.80
L1	-	3.10	3.40
ΦP	3.40	3.60	3.80
Q	2.60	2.80	3.00



HYG040N13NS1P/B

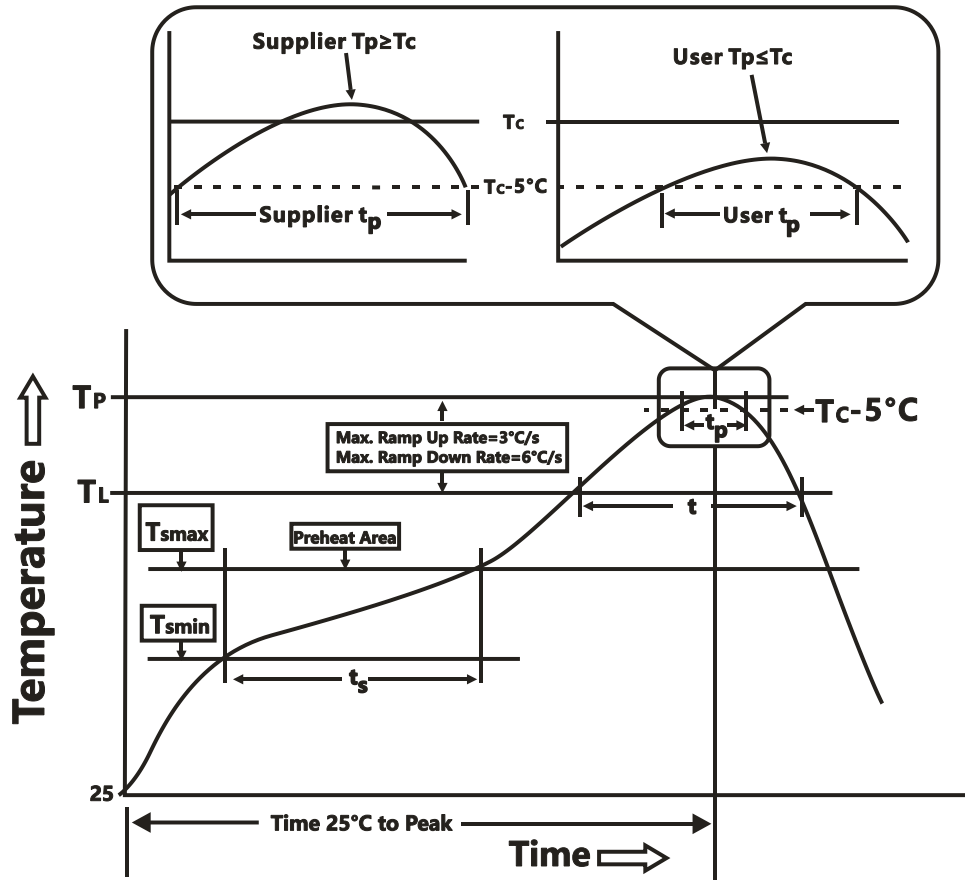
TO-263-2L



COMMON DIMENSIONS			
SYMBOL	mm		
	MIN	NOM	MIN
A	4.37	4.57	4.77
A1	1.22	1.27	1.42
A2	2.49	2.69	2.89
A3	0	0.13	0.25
b	0.70	0.81	0.96
b1	1.17	1.27	1.47
c	0.30	0.38	0.53
D1	8.50	8.70	8.90
D4	6.60	-	-
E	9.86	10.16	10.36
E5	7.06	-	-
e	2.54 BSC		
H	14.70	15.10	15.50
H2	1.07	1.27	1.47
L	2.00	2.30	2.60
L1	1.40	1.55	1.70
L4	0.25 BSC		
θ	0°	5°	9°



## Classification Profile



## Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
<b>Preheat &amp; Soak</b>		
Temperature min ( $T_{min}$ )	100 °C	150 °C
Temperature max ( $T_{max}$ )	150 °C	200 °C
Time ( $T_{min}$ to $T_{max}$ ) ( $t_s$ )	60-120 seconds	60-120 seconds
Average ramp-up rate ( $T_{max}$ to $T_P$ )	3 °C/second max.	3°C/second max.
Liquidous temperature ( $T_L$ )	183 °C	217 °C
Time at liquidous ( $t_L$ )	60-150 seconds	60-150 seconds
Peak package body Temperature ( $T_P$ )*	See Classification Temp in table 1	See Classification Temp in table 2
Time ( $t_P$ )** within 5°C of the specified classification temperature ( $T_c$ )	20** seconds	30** seconds
Average ramp-down rate ( $T_P$ to $T_{max}$ )	6 °C/second max.	6 °C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.
*Tolerance for peak profile Temperature ( $T_P$ ) is defined as a supplier minimum and a user maximum.		
** Tolerance for time at peak profile temperature ( $t_P$ ) is defined as a supplier minimum and a user maximum.		

Table 1.SnPb Eutectic Process – Classification Temperatures (Tc)

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2.Pb-free Process – Classification Temperatures (Tc)

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350-2000	Volume mm <sup>3</sup> ≥2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

## Reliability Test Program

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HTRB	JESD-22, A108	168/500/1000 Hrs, Bias @ 150°C
HTGB	JESD-22, A108	168/500/1000 Hrs, V <sub>gs</sub> 100% @ 150°C
PCT	JESD-22, A102	96 Hrs, 100%RH, 2atm, 121°C
TCT	JESD-22, A104	250/500/1000 Cycles, -55°C~150°C

## Customer Service

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